Facile electrochemical synthesis of 3D nano-architectured CuO

electrodes for high-performance supercapacitors

Ming-Jay Deng^{a†*}, Cheng-Chia Wang^{a,b†}, Pei-Jung Ho^{a,c}, Chih-Ming Lin^c, Jin-Ming

Chen^a*, Kueih-Tzu Lu^a*

a National Synchrotron Radiation Research Center, Hsinchu, Taiwan.

b Department of Materials Science and Engineering, National Chiao Tung University,

Hsinchu, Taiwan

c Department of Applied Science, National Hsinchu University of Education, Hsinchu,

Taiwan

E-mail: deng.mj@nsrrc.org.tw or martinez730523@yahoo.com.tw ;

jmchen@nsrrc.org.tw; ktlu@nsrrc.org.tw



Figure S1 Cyclic voltammogram of the Ni foam electrode in solution (NiSO₄ 0.5 M ,

NiCl₂ 0.5 M , CuSO₄ 0.01 M, H₃BO₃ 1 M) at potential scan rate 10 mV s⁻¹.



Figure S2 SEM micrographs of Ni-Cu alloy films that were electrodeposited at (a) - 0.70V and (b) -0.85V followed by selective dissolution at 0.80 V.



Figure S3 Nyquist plots of three electrodes for supercapacitors.



Figure S4 Capacitance-retention ratios as a function of the CV scan rate for CNRNP, CNFNF, FLC, CNRNP', CNFNF' and FLC' electrodes. The amounts of deposited CuO were 0.32 mg cm⁻² (curves CNRNP, CNFNF, FLC) and 1.2 mg cm⁻² (curves CNRNP', CNFNF', FLC').



Figure S5 Cycle performance of the CNRNP, CNFNF and FLC electrodes.